# mail

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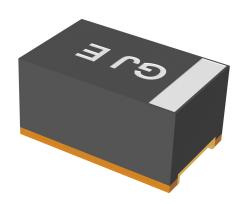


#### **Overview**

The T488 Series uses a substrate termination design, which results in one of the highest volumetric efficient packaging technologies available today in Tantalum Chip Capacitors. This series offers high capacitance values in the small EIA 2012-12

**Benefits** 

- Tantalum Technology
- · Substrate Termination
- EIA Case Size 2012 (0805 MLCC Equivalent)
- Low Profile: 1.2 mm maximum
- Improved Volumetric Efficiency
- Use up to 80% of rated voltage (20% derating)
- Capacitance: 220 µF
- Voltage: 4 V
- · RoHS Compliant and Halogen Free
- 125°C maximum temperature capability
- Lead free 260°C reflow capable
- MSL Reflow Temp ≤ 260°C = 1



(2.0 mm (L) x 1.2 mm (W) x 1.2 mm (H)) package size. The T488

Series is ideal for use in densely populated circuits such as smart phones and digital cameras where space restrictions do not allow

for larger and more commonly available case sizes.

#### **Applications**

Typical applications include densely populated circuits where space restrictions do not allow for larger and more commonly available case sizes such as smart phones, digital cameras, MP3 players, GPS navigation systems, WiFi modules, analytical and test equipment, and audio/sound circuits.

#### **Environmental Compliance**

RoHS Compliant (6/6) according to Directive 2002/95/EC. Halogen free.









### **Ordering Information**

Т	488	R	227	М	004	Α	Α	E2K0
Capacitor Class	Series	Case Size	Capacitance Code (pF)	Capacitance Tolerance	Voltage	Failure Rate/ Design	Lead Material	ESR Code
T = Tantalum	Substrate Terminal MnO <sub>2</sub>	R = 2012	First two digits represent significant figures. Third digit specifies number of zeros. e.g., 227 = 220 µF	M = ±20%	004 = 4 V	A = N/A	A = Ni - Au	E = ESR Last three digits specify ESR in m $\Omega$ (2K0 = 2,000 m $\Omega$ )

#### **Performance Characteristics**

Item	Specifications
Operating Temperature	-55°C to 125°C
Rated Capacitance Range	220 μF @ 120 Hz/25°C
Capacitance Tolerance	M Tolerance (20%)
Rated Voltage Range	4 V
ESR (100 kHz)	Refer to Part Number Electrical Specification Table
Leakage Current	$\leq$ 0.1 CV (µA) at rated voltage after 5 minutes



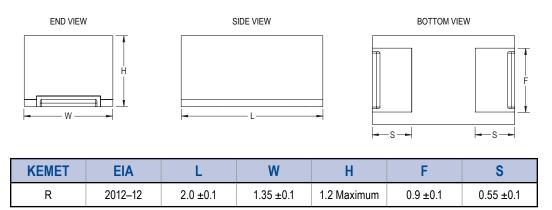
#### Qualification

Test	Condition/Characteristics				
		ΔC/C	Within initial $\Delta$ C/C limits		
Endurance	85°C @ rated voltage, 1,000 hours		DF	Within 1.5 x initial limi	ts
			DCL	Within initial limit	
			ΔC/C	Within ±20% of initial	∆ C/C limits
Damp Heat Steady State	40°C, 90 to 95% RH, 500 hours		DF	Within 1.5 x initial limi	ts
		DCL	Within initial limit		
			+25°C	-55°C	+125°C
To reactive Otability	Extreme temperature exposure at -55°C and +125°C	ΔC/C	IL*	-20% to 0% of ∆ C/C	-50% - 0% of Δ C/C
Temperature Stability		DF	IL	IL	IL
		DCL	IL	IL	1.25 CV
			ΔC/C	Within initial $\Delta$ C/C lim	nits
Surge Voltage	1.3 Vr, 85°C, 1,000 Ω resistor, 1,000 c	DF	Within initial limit		
			DCL	Within initial limit	
			ΔC/C	Within initial $\Delta$ C/C lim	nits
Mechanical Shock	100 G, Saw-Tooth wave		DF	Within initial limit	
			DCL	Within initial limit	
	Frequency: 10 to 2 kHz, Sweep: 1 min	nute.	ΔC/C	Within initial $\Delta$ C/C limits	
Vibration	Amplitude of vibration: 1.5 mm, Vibrat	ion Time:	DF	Within initial limit	
	Each plane shall be 2 hours for a total of 4 hours.		DCL	Within initial limit	
Terminal strength	Strength: 4.9 N, Time: 10 ±0.5 second (two directions)	Visual	No evidence of mecha	anical damage	

\*IL = Initial limit

#### **Dimensions – Millimeters**

Metric will govern





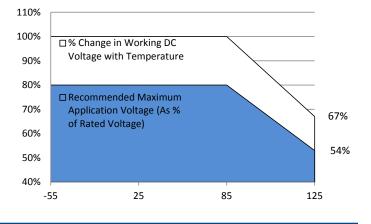
#### Table 1 – Ratings & Part Number Reference

Rated Voltage	Rated Capacitance	Case Code/ Case Size	KEMET Part Number	DC Leakage	DF	ESR		num Allo ople Curre		Rated Temp.
VDC	μF	KEMET/EIA	(See below for part options)	µA @ +20°C Maximum/ 5 Minutes	% @ +20°C 120 Hz Maximum	Ω @ +20°C 100 kHz Maximum	(mA) 100 kHz, 25°C	(mA) 100 kHz, 85°C	(mA) 100 kHz, 125°C	°C
4	220	R/2012-12	T488R227M004AAE2K0	88.0	6.0	2	224	202	90	125

Refer to Ordering Information for additional detail.

#### **Recommended Voltage Derating Guidelines**

	-55°C to 85°C	85°C to 125°C
% Change in Working DC Voltage with Temperature		See Chart
Recommended Maximum Application Voltage	80% of $V_{\text{R}}$	See Chart



#### **Ripple Current/Ripple Voltage**

Permissible AC ripple voltage and current are related to equivalent series resistance (ESR) and the power dissipation capabilities of the device. Permissible AC ripple voltage which may be applied is limited by two criteria:

1. The positive peak AC voltage plus the DC bias voltage, if any, must not exceed the DC voltage rating of the capacitor.

2. The negative peak AC voltage in combination with bias voltage, if any, must not exceed the allowable limits specified for reverse voltage. See the Reverse Voltage section for allowable limits.

The maximum power dissipation by case size can be determined using the table at right. The maximum power dissipation rating stated in the table must be reduced with increasing environmental operating temperatures. Refer to the table below for temperature compensation requirements.

Temperature Compensation Multipliers for Maximum Ripple Current						
T ≤ 25°C T ≤ 85°C T ≤ 125°C						
1.00 0.90 0.40						

KEMET Case Code	EIA Case Code	Maximum Power Dissipation (P max) mWatts @ 25°C w/+20°C Rise
R	2012-12	25

The maximum power dissipation rating must be reduced with increasing environmental operating temperatures. Refer to the Temperature Compensation Multiplier table for details.

T= Environmental Temperature

Using the P max of the device, the maximum allowable rms ripple current or voltage may be determined.

 $I(max) = \sqrt{P max/R}$  $E(max) = Z \sqrt{P max/R}$ 

I = rms ripple current (amperes)

- E = rms ripple voltage (volts)
- P max = maximum power dissipation (watts)
- R = ESR at specified frequency (ohms)
- Z = Impedance at specified frequency (ohms)

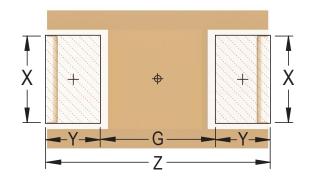


#### **Reverse Voltage**

Solid tantalum capacitors are polar devices and may be permanently damaged or destroyed if connected with the wrong polarity. The positive terminal is identified on the capacitor body by a stripe plus in some cases a beveled edge. A small degree of transient reverse voltage is permissible for short periods per the table. The capacitors should not be operated continuously in reverse mode, even within these limits.

Temperature	Permissible Transient Reverse Voltage
25°C	15% of Rated Voltage
85°C	5% of Rated Voltage
125°C	1% of Rated Voltage

#### Table 2 – Land Dimensions/Courtyard



KEMET	Metric Size Code	Dimensions in mm					
Case	EIA	G Maximum	Z Minimum	X Minimum	Y ref		
R	2012–12	1.05	2.05	0.80	1.05		



#### **Soldering Process**

KEMET's families of surface mount capacitors are compatible with wave (single or dual), convection, IR, or vapor phase reflow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET's recommended profile conditions for convection and IR reflow reflect the profile conditions of the IPC/J–STD–020D standard for moisture sensitivity testing. The devices can safely withstand a maximum of three reflow passes at these conditions.

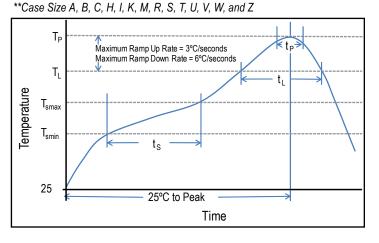
Note that although the X/7343–43 case size can withstand wave soldering, the tall profile (4.3 mm maximum) dictates care in wave process development.

Hand soldering should be performed with care due to the difficulty in process control. If performed, care should be taken to avoid contact of the soldering iron to the molded case. The iron should be used to heat the solder pad, applying solder between the pad and the termination, until reflow occurs. Once reflow occurs, the iron should be removed immediately. "Wiping" the edges of a chip and heating the top surface is not recommended.

During typical reflow operations, a slight darkening of the goldcolored epoxy may be observed. This slight darkening is normal and not harmful to the product. Marking permanency is not affected by this change.

Profile Feature	SnPb Assembly	Pb-Free Assembly
Preheat/Soak		
Temperature Minimum (T <sub>Smin</sub> )	100°C	150°C
Temperature Maximum (T <sub>Smax</sub> )	150°C	200°C
Time (t <sub>s</sub> ) from $T_{smin}$ to $T_{smax}$ )	60 – 120 seconds	60 – 120 seconds
Ramp-up Rate (T <sub>L</sub> to T <sub>P</sub> )	3°C/seconds maximum	3°C/seconds maximum
Liquidous Temperature (T <sub>L</sub> )	183°C	217°C
Time Above Liquidous $(t_L)$	60 – 150 seconds	60 – 150 seconds
Peak Temperature (T <sub>P</sub> )	220°C* 235°C**	250°C* 260°C**
Time within 5°C of Maximum Peak Temperature (t <sub>P</sub> )	20 seconds maximum	30 seconds maximum
Ramp-down Rate $(T_P \text{ to } T_L)$	6°C/seconds maximum	6°C/seconds maximum
Time 25°C to Peak Temperature	6 minutes maximum	8 minutes maximum

Note: All temperatures refer to the center of the package, measured on the package body surface that is facing up during assembly reflow. \*Case Size D, E, P, Y, and X

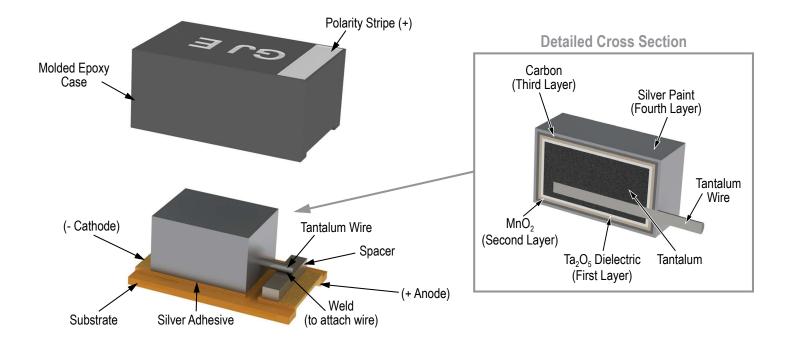


#### Storage

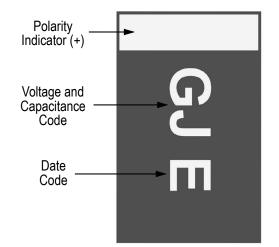
The T488 Series is shipped in moisture barrier bags with a desiccant and moisture indicator card. This series is classified as MSL3 (Moisture Sensitivity Level 3). Product contained within the moisture barrier bags should be stored in normal working environments with temperatures not to exceed 30°C and humidity not in excess of 60% RH.



#### Construction



## **Capacitor Marking**



Code	G
Rated Voltage	4 V

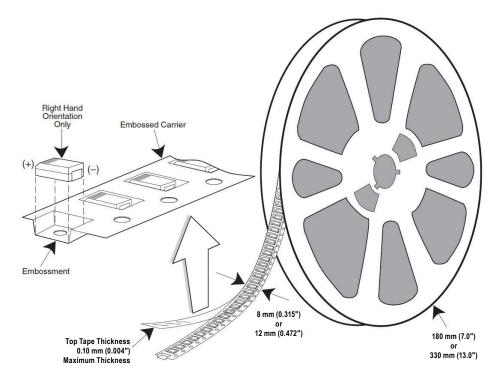
Code	J
Capacitance	220

	Date Code *											
	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
2013	А	В	С	D	E	F	G	Н	J	К	L	М
2014	N	Р	Q	R	S	Т	U	V	W	Х	Y	Z
2015	а	b	С	d	е	f	g	h	j	k	I	m
2016	n	р	q	r	S	t	u	v	w	x	у	z



#### **Tape & Reel Packaging Information**

KEMET's molded tantalum and aluminum chip capacitor families are packaged in 8 and 12 mm plastic tape on 7" and 13" reels in accordance with *EIA Standard 481*: Embossed Carrier Taping of Surface Mount Components for Automatic Handling. This packaging system is compatible with all tape-fed automatic pick-and-place systems.



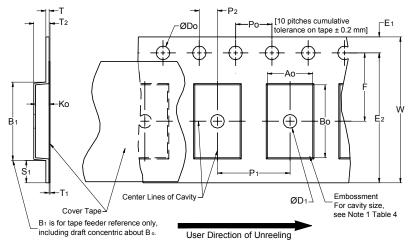
#### Table 3 – Packaging Quantity

		Tape and Reel Dimensions				
KEMETC	ase Codes	Tape Width (mm)	180 mm (7" diameter)			
R	2012	8	3,000			

(Quantity per reel)



#### Figure 1 – Embossed (Plastic) Carrier Tape Dimensions



#### Table 4 – Embossed (Plastic) Carrier Tape Dimensions

Metric will govern

Constant Dimensions — Millimeters (Inches)									
Tape Size	D <sub>0</sub>	D <sub>1</sub> Minimun Note 1	n E <sub>1</sub>	P <sub>0</sub>	P <sub>2</sub>	R Reference Note 2	S <sub>1</sub> Minimum Note 3	T Maximum	T <sub>1</sub> Maximum
8 mm		1.0 (0.039)			2.0 ±0.05	25.0 (0.984)			
12 mm	1.5 +0.10/-0.0 (0.059 +0.004/-0		1.75 ±0.10 (0.069 ±0.0)		· · · · · · · · · · · · · · · · · · ·	30	0.600 (0.024)	0.600 (0.024)	0.100 (0.004)
16 mm		(0.059)			2.0 ±0.1 (0.079 ±0.059)	(1.181)		. ,	
Variable Dimensions — Millimeters (Inches)									
Tape Size	Pitch	B <sub>1</sub> Maximum Note 4	E <sub>2</sub> Minimum	F	P <sub>1</sub>		T <sub>2</sub> Maximum	W Maximum	A <sub>0</sub> , B <sub>0</sub> & K <sub>0</sub>
8 mm	Single (4 mm)	4.35 (0.171)	6.25 (0.246)	3.5 ±0.05 (0.138 ±0.002)	2.0 ±0.05 or 4. (0.079 ±0.002 or 0.		2.5 (0.098)	8.3 (0.327)	
12 mm	Single (4 mm) & Double (8 mm)	8.2 (0.323)	10.25 (0.404)	5.5 ±0.05 (0.217 ±0.002)	±0.10 (0.157 ±0.004	2.0 ±0.05 (0.079 ±0.002) or 4.0 0.10 (0.157 ±0.004) or 8.0 ±0.10 (0.315 ±0.004)		12.3 (0.484)	Note 5
16 mm	Triple (12 mm)	12.1	14.25	$7.5 \pm 0.10$	4.0 ±0.10 (0.157 ±0		8.0 (0.315)	16.3	

1. The embossment hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of embossment location and hole location shall be applied independent of each other.

±0.10 (0.472 ±0.004)

(0.295 ±0.004)

2. The tape, with or without components, shall pass around R without damage (see Figure 4).

3. If S<sub>1</sub> < 1.0 mm, there may not be enough area for cover tape to be properly applied (see EIA Standard 481–D, paragraph 4.3, section b).

4. B, dimension is a reference dimension for tape feeder clearance only.

(0.476)

5. The cavity defined by  $A_{\alpha}$ ,  $B_{\alpha}$  and  $K_{\alpha}$  shall surround the component with sufficient clearance that:

(a) the component does not protrude above the top surface of the carrier tape.

(b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.

(c) rotation of the component is limited to 20° maximum for 8 and 12 mm tapes and 10° maximum for 16 mm tapes (see Figure 2).

(d) lateral movement of the component is restricted to 0.5 mm maximum for 8 mm and 12 mm wide tape and to 1.0 mm maximum for 16 mm tape (see Figure 3).

(e) see Addendum in EIA Standard 481–D for standards relating to more precise taping requirements.

(0.561)

(0.642)



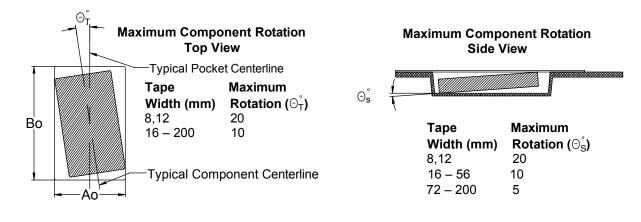
#### **Packaging Information Performance Notes**

- 1. Cover Tape Break Force: 1.0 Kg minimum.
- 2. Cover Tape Peel Strength: The total peel strength of the cover tape from the carrier tape shall be:

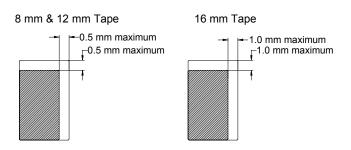
Tape Width	Peel Strength			
8 mm	0.1 to 1.0 Newton (10 to 100 gf)			
12 and 16 mm	0.1 to 1.3 Newton (10 to 130 gf)			

The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be  $165^{\circ}$  to  $180^{\circ}$  from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of  $300 \pm 10$  mm/minute. **3. Labeling:** Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. *Refer to EIA Standards* 556 *and* 624.

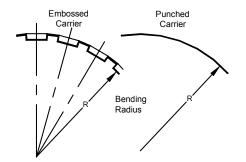
#### Figure 2 – Maximum Component Rotation



#### Figure 3 – Maximum Lateral Movement

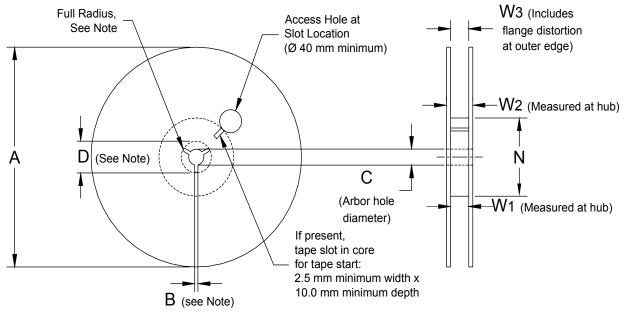


#### Figure 4 – Bending Radius





#### Figure 5 – Reel Dimensions



Note: Drive spokes optional; if used, dimensions B and D shall apply.

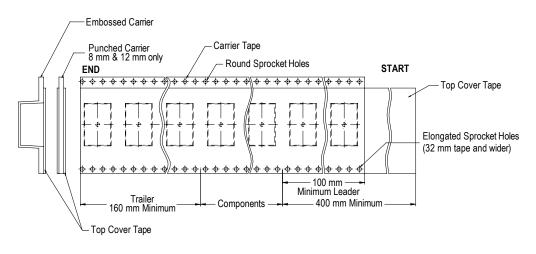
#### Table 5 – Reel Dimensions

Metric will govern

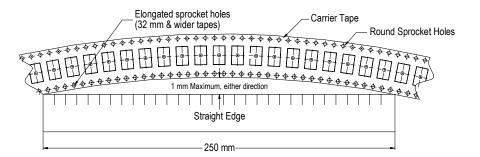
Constant Dimensions — Millimeters (Inches)								
Tape Size	А	B Minimum	С	D Minimum				
8 mm	178 ±0.20 (7.008 ±0.008)	1.5 (0.059)	13.0 +0.5/-0.2 (0.521 +0.02/-0.008)					
12 mm	or			20.2 (0.795)				
16 mm	330 ±0.20 (13.000 ±0.008)	(0.000)		(0.00)				
	Variable Dimensions — Millimeters (Inches)							
Tape Size	N Minimum	W <sub>1</sub>	W <sub>2</sub> Maximum	W <sub>3</sub>				
8 mm		8.4 +1.5/-0.0 (0.331 +0.059/-0.0)	14.4 (0.567)					
12 mm	50 (1.969)	12.4 +2.0/-0.0 (0.488 +0.078/-0.0)	18.4 (0.724)	Shall accommodate tape width without interference				
16 mm	· · ·	16.4 +2.0/-0.0 (0.646 +0.078/-0.0)	22.4 (0.882)					



#### Figure 6 – Tape Leader & Trailer Dimensions



#### Figure 7 – Maximum Camber





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